## MOSFET – Power, N-Channel, Automotive SUPERFET<sup>®</sup> III, Easy-drive

**650 V, 75 A, 25 m**Ω

#### **Description**

SuperFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET Easy-drive series helps manage EMI issues and allows for easier design implementation.

#### **Features**

- AEC-Q101 Qualified
- Max Junction Temperature 150°C
- Typ.  $R_{DS}(on) = 19.9 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>G</sub> = 236 nC)
- Low Effective Output Capacitance (Typ. C<sub>OSS</sub>(eff.) = 2062 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### **Typical Applications**

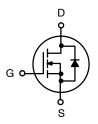
- Automotive PHEV-BEV DC-DC Converter
- Automotive Onboard Charger for PHEV-BEV



#### ON Semiconductor®

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BV <sub>DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
650 V	25 m $\Omega$ @ $10$ V	75 A

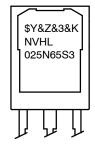


**N-Channel MOSFET** 



TO-247-3LD CASE 340CX

#### **MARKING DIAGRAM**



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

NVHL025N65S3

#### **ORDERING INFORMATION**

= Specific Device Code

See detailed ordering and shipping information on page 2 of this data sheet.

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		650	V
$V_{GSS}$	Gate to Source Voltage	DC Positive	30	V
		AC Positive, (f > 1 Hz)	30	V
		AC Negative, (f > 1 Hz)	-20	V
I <sub>D</sub>	Drain Current	Continuous (Tc = 25°C)	75	Α
		Continuous (Tc = 100°C)	65.8	Α
I <sub>DM</sub>	Pulsed Drain Current	Pulsed (Note 1)	187.5	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		2025	mJ
E <sub>AR</sub>	Repetitive Avalanche (Note 1)		5.95	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	V/ns
P <sub>D</sub>	Power Dissipation	(Tc = 25°C)	595	W
		Derate Above 25°C	4.76	W/°C
$T_J$ , $T_{STG}$	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse–width limited by maximum junction temperature.

2.  $I_{AS} = 15 \text{ A}$ ,  $R_{G} = 25 \Omega$ , starting  $T_{J} = 25^{\circ}\text{C}$ .

3.  $I_{SD} < 75 \text{ A}$ , di/dt  $\leq 200 \text{ A/ms}$ , VDD  $\leq \text{BVDSS}$ , starting  $T_{J} = 25^{\circ}\text{C}$ .

- 4. Essentially independent of operating temperature typical characteristics.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R <sub>θJ C</sub>	Thermal Resistance, Junction to Case, Max	0.21	°C/W
$R_{ heta J A}$	Thermal Resistance, Junction to Ambient, Max	40	°C/W

#### PACKAGE MARKING AND ORDERING INFORMATION

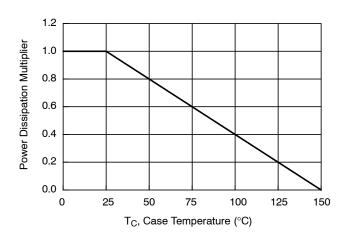
Part Number	Top Marking	Package	Packing Method	Shipping (Qty / Packing)
NVHL025N65S3	NVHL025N65S3	TO-247-3LD	Tube	30 Units / Tube

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•			
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C	650	713	_	V
		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	650	755	-	V
ΔBVDSS / ΔTJ	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.34	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V	-	0.30	1	μΑ
		V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V, Tc = 125°C	-	7.92	-	
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = +30 V, V <sub>DS</sub> = 0 V	-	5.27	+100	nA
		V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V	-	2.65	-100	nA
ON CHARACTE	RISTICS					
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 3.0 \text{ mA}$	2.5	3.56	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 37.5 A, T <sub>J</sub> = 25°C	-	19.9	25	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 37.5 A, T <sub>J</sub> = 100°C	-	34.6	-	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 75 A	-	78.5	-	S
OYNAMIC CHAI	RACTERISTICS		•	•	•	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	7330	-	pF
C <sub>oss</sub>	Output Capacitance		-	197	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		_	33.6	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	2062	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	285	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A	-	236	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 4)	-	59.3	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	97.3	-	nC
R <sub>G</sub>	Gate Resistance	f = 1 MHz	-	0.818	-	mΩ
SWITCHING CH	ARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 75 A, V <sub>GS</sub> = 10 V,	_	43.3	-	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 2 \Omega$ (Note 4)	_	109	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		_	120	-	ns
t <sub>f</sub>	Fall Time		_	107	-	ns
DRAIN-SOURC	E DIODE CHARACTERISTICS		-	-	-	-
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	75	Α
I <sub>SM</sub>	Maximum Plused Drain to Source Diode Forward Current		-	-	300	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 37.5 A	-	0.88	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{SD} = 75 \text{ A } dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	714	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge	1	_	26.4	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**



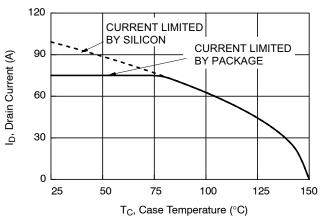


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs. Case Temperature

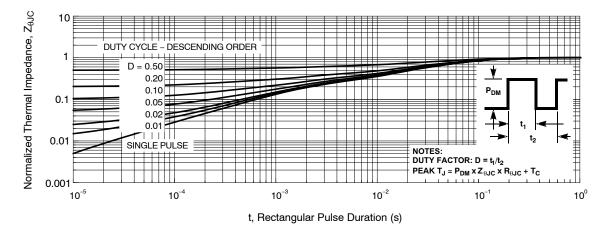


Figure 3. Normalized Maximum Transient Thermal Impedance

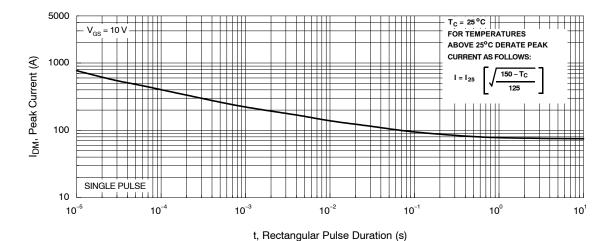


Figure 4. Peak Current Capability

#### TYPICAL CHARACTERISTICS (continued)

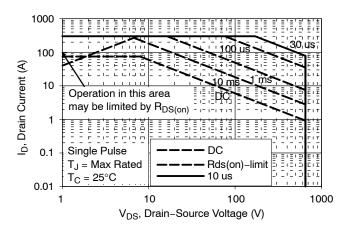


Figure 5. Forward Bias Safe Operating Area

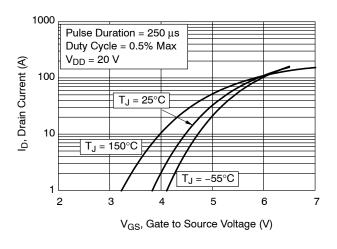


Figure 7. Transfer Characteristic

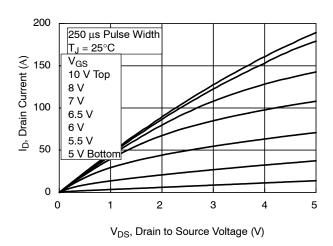
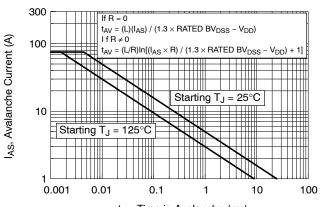


Figure 9. Saturation Characteristics



t<sub>AV</sub>, Time in Avalanche (ms) NOTES: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

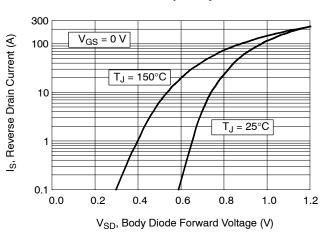


Figure 8. Forward Diode Characteristics

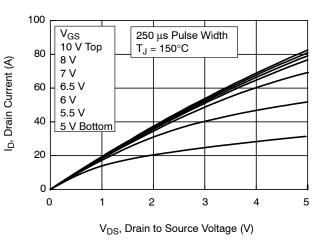
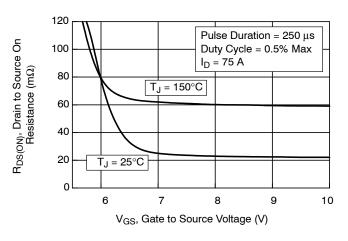


Figure 10. Saturation Characteristics

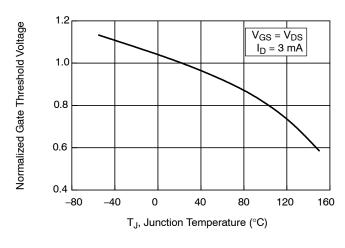
#### TYPICAL CHARACTERISTICS (continued)



3.0 Pulse Duration = 250 μs Normalized Drain to Source 2.5 Duty Cycle = 0.5% Max ON-Resistance 2.0 1.5 I<sub>D</sub> = 75 A 1.0 V<sub>GS</sub> = 10 V 0.5 0.0 -80 -40 40 80 120 160 T<sub>J</sub>, Junction Temperature (°C)

Figure 11. R<sub>DSON</sub> vs. Gate Voltage

Figure 12. Normalized R<sub>DSON</sub> vs. Junction Temperature



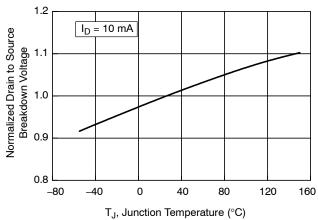
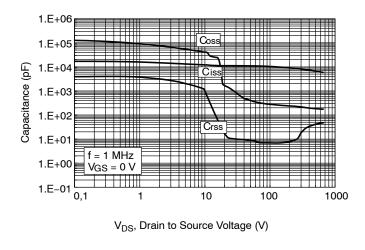


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature



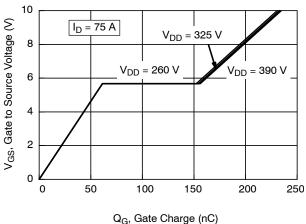


Figure 15. Capacitance vs. Drain to Source Volatage

Figure 16. Gate Charge vs. Gate to Source Voltage

#### TYPICAL CHARACTERISTICS (continued)

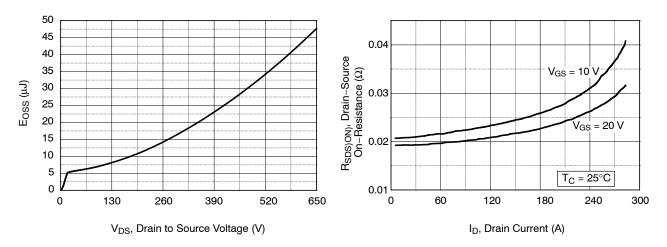
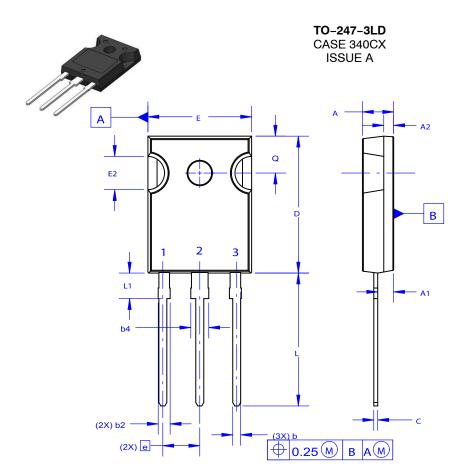


Figure 17. E<sub>OSS</sub> vs. Drain to Source Voltage

Figure 18. On–Resistance Variation vs. Drain Current and Gate Voltage

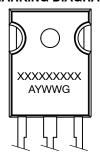
**DATE 06 JUL 2020** 



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

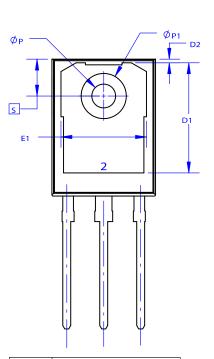
# GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
<b>A</b> 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
E	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
ØP1	6.60	6.80	7.00	

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